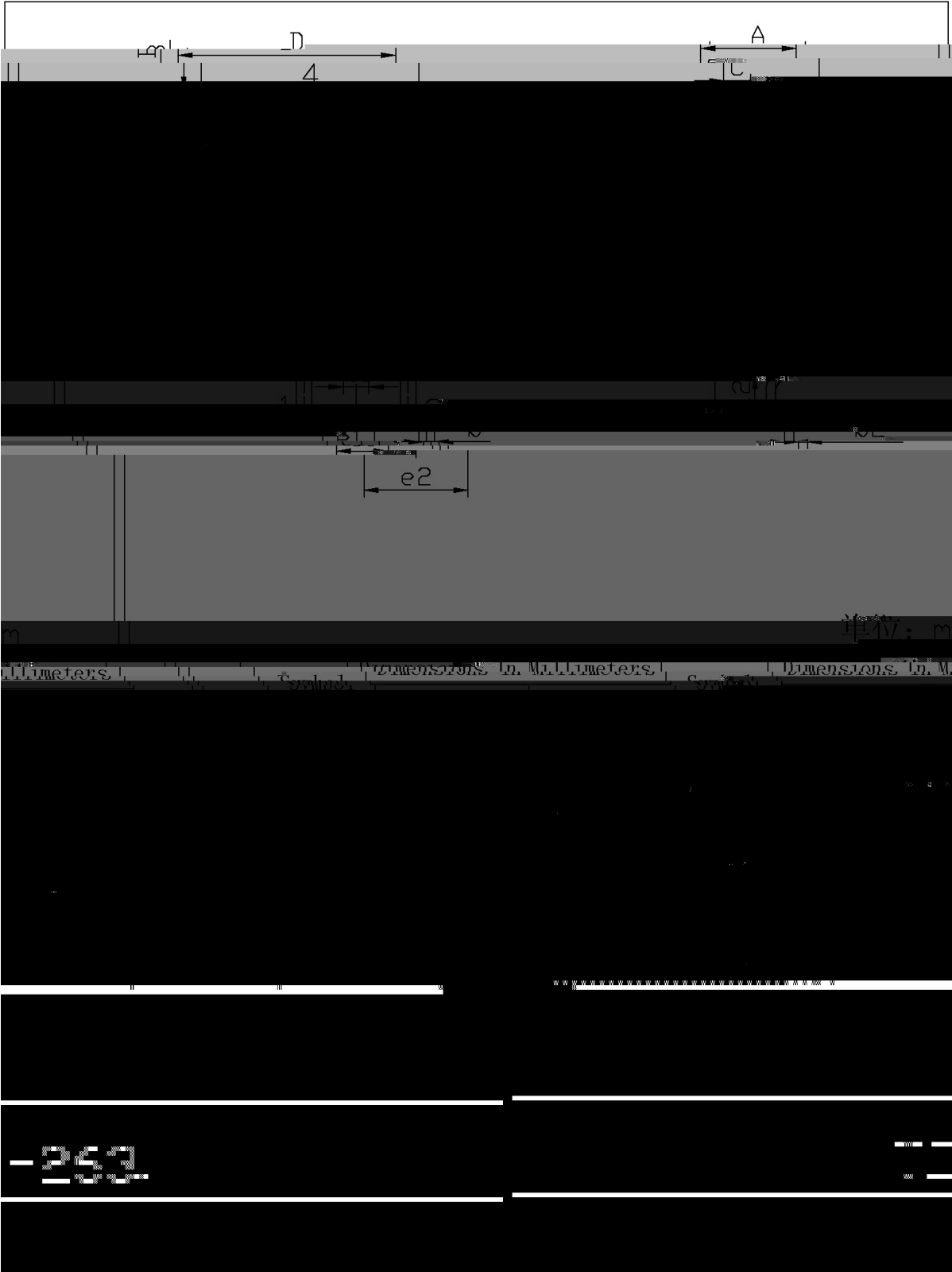


/ Electrical Characteristic Curve

/ Package Dimensions



() / Temperature Profile for IR Reflow Soldering(Pb-Free)

- 備 註
- 1 150℃~200℃ 10~120sec;

2 255℃±5℃ 10~120sec;

3 2~10℃/sec.

Note:

1.Preheating:150~200℃ , Time:60~120sec.

2.Peak Temp.:255℃±5℃ , Duration:10~120sec.

3. Cooling Speed: 2~10℃/sec.

/ Resistance to Soldering Heat Test Conditions

605℃±5℃